Vincotech

10-FE06PPA050SJ01-LH54E08Z
datasheet

***flow*PIM 1 + PFC** **600 V / 50 A**

Topology features

- 2-leg interleaved PFC + Inverter
- On-board Capacitors
- Open Emitter configuration
- Shunt
- Temperature sensor

Component features

- 5us short circuit withstand time
- High speed switching
- Low EMI
- Short tail current

Housing features

- Base isolation: Al_2O_3
- Convex shaped substrate for superior thermal contact
- Solder pin
- Thermo-mechanical push-and-pull force relief

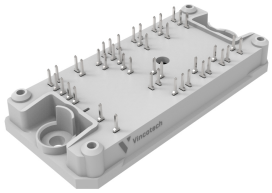
Target applications

- Embedded Drives
- Industrial Drives

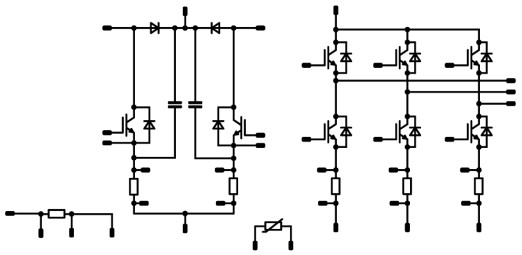
Types

- 10-FE06PPA050SJ01-LH54E08Z

flow 1 12 mm housing



Schematic



Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		600	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ T_s = 80 °C	49	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	81	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V, V_{CC} = 400 V T_j = 150 °C	5	µs
Maximum junction temperature	T_{jmax}		175	°C
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		600	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ T_s = 80 °C	36	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	60	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	58	W
Maximum junction temperature	T_{jmax}		175	°C
PFC Switch				
Collector-emitter voltage	V_{CES}		650	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ T_s = 80 °C	47	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	150	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	81	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
PFC Diode				
Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	T_j = T_{jmax} T_s = 80 °C	49	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	84	W
Maximum junction temperature	T_{jmax}		175	°C
PFC Sw. Protection Diode				
Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	T_j = T_{jmax} T_s <= 80 °C	20 (1)	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	20	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	33	W
Maximum junction temperature	T_{jmax}		175	°C
Inverter Shunt				
DC current	I		31,6	A
Power dissipation	P_{tot}	T_c = 70 °C	2	W
Operation Temperature	T_{op}		-65 ... 170	°C
PFC Shunt				
DC current	I		31,6	A
Power dissipation	P_{tot}	T_c = 70 °C	2	W
Operation Temperature	T_{op}		-65 ... 170	°C
Shunt				
DC current	I		63,2	A
Power dissipation	P_{tot}	T_c = 70 °C	4	W
Operation Temperature	T_{op}		-65 ... 170	°C

(1) limited by I_{FRM}

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Capacitor (PFC)				
Maximum DC voltage	V_{MAX}		630	V
Operation Temperature	T_{op}		-55 ... 150	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…+(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
Creepage distance			>12,7	mm
Clearance			8,56	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,0008	25	4,1	5,1	5,7	V
Collector-emitter saturation voltage	V_{CEsat}		15		50	25 125 150		1,49 1,61 1,64	1,8[2]	V
Collector-emitter cut-off current	I_{CES}		0	600		25			2,8	µA
Gate-emitter leakage current	I_{GES}		20	0		25			100	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		1950		pF
Output capacitance	C_{oes}							83		pF
Reverse transfer capacitance	C_{res}							67		pF
Gate charge	Q_g	V_{CC} = 480 V	15		50	25		249		nC
Thermal										
Thermal resistance junction to sink[3]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,18		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 8 Ω R_{goff} = 8 Ω	±15	350	50	25 125 150		70 70 71,2		ns
Rise time	t_r					25 125 150		45,2 43,2 42,8		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		114,8 133,6 138,6		ns
Fall time	t_f					25 125 150		22,47 34,2 41,12		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=1,62 µC Q_{rFWD}=3,09 µC Q_{rFWD}=3,57 µC				25 125 150		1,84 2,2 2,28		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,536 0,839 0,941		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				30	25 150	1,25	1,64 1,55	1,95(2)	V
Reverse leakage current	I_R	V_r = 600 V				25			27	µA
Thermal										
Thermal resistance junction to sink(3)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,63		K/W
Dynamic										
Peak recovery current	I_{RM}	di/dt=245 A/µs di/dt=545 A/µs di/dt=378 A/µs	±15	350	50	25 125 150		10,63 16,09 16,77		A
Reverse recovery time	t_{rr}					25 125 150		251,47 331,66 392,82		ns
Recovered charge	Q_r					25 125 150		1,62 3,09 3,57		µC
Reverse recovered energy	E_{rec}					25 125 150		0,406 0,762 0,892		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		76,03 88,46 100,72		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	V_{CE} = V_{GE}			0,0005	25	3,3	4	4,7	V
Collector-emitter saturation voltage	V_{CEsat}		15		50	25 125 150		1,52 1,64 1,7	2,22(2)	V
Collector-emitter cut-off current	I_{CES}		0	650		25			40	µA
Gate-emitter leakage current	I_{GES}		20	0		25			120	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	f = 1 Mhz	0	25		25		3000		pF
Output capacitance	C_{oes}							50		pF
Reverse transfer capacitance	C_{res}							11		pF
Gate charge	Q_g	V_{CC} = 520 V	15		50	25		120		nC
Thermal										
Thermal resistance junction to sink(3)	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,17		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 4 Ω R_{goff} = 4 Ω	0/15	400	50	25 125 150		14,8 13,4 15,2		ns
Rise time	t_r					25 125 150		6 7,2 7,6		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		81,6 97,2 100,6		ns
Fall time	t_f					25 125 150		2,69 6,04 8,15		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD}=0,941 µC Q_{rFWD}=1,79 µC Q_{rFWD}=2,27 µC				25 125 150		0,429 0,668 0,69		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,152 0,383 0,471		mWs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Diode										
Static										
Forward voltage	V_F				50	25 125 150		2,17 1,87 1,8	2,6[2]	V
Reverse leakage current	I_R	V_r = 650 V				25			10	µA
Thermal										
Thermal resistance junction to sink[3]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,14		K/W
Dynamic										
Peak recovery current	I_{RM}	di/dt=6122 A/µs di/dt=5344 A/µs di/dt=4864 A/µs	0/15	400	50	25 125 150		63,34 83,08 91,81		A
Reverse recovery time	t_{rr}					25 125 150		16,75 46,6 53,79		ns
Recovered charge	Q_r					25 125 150		0,941 1,79 2,27		µC
Reverse recovered energy	E_{rec}					25 125 150		0,212 0,37 0,547		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		14126 8573 6729		A/µs

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
PFC Sw. Protection Diode										
Static										
Forward voltage	V_F				10	25 125	1,23	1,67 1,54	1,87[2]	V
Reverse leakage current	I_R	V_r = 650 V				25			0,14	µA
Thermal										
Thermal resistance junction to sink[3]	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,87		K/W
Inverter Shunt										
Static										
Resistance	R							2		mΩ
Temperature coeficient	tc								275	ppm/K
PFC Shunt										
Static										
Resistance	R							2		mΩ
Temperature coeficient	tc								275	ppm/K
Shunt										
Static										
Resistance	R							1		mΩ
Temperature coeficient	tc								275	ppm/K

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Capacitor (PFC)										
Static										
Capacitance	C	DC bias voltage = 0 V				25		33		nF
Tolerance							-5		5	%
Thermistor										
Static										
Rated resistance	R					25		22		kΩ
Deviation of R100	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %						4000		K
Vincotech Thermistor Reference									I	

(2) Value at chip level

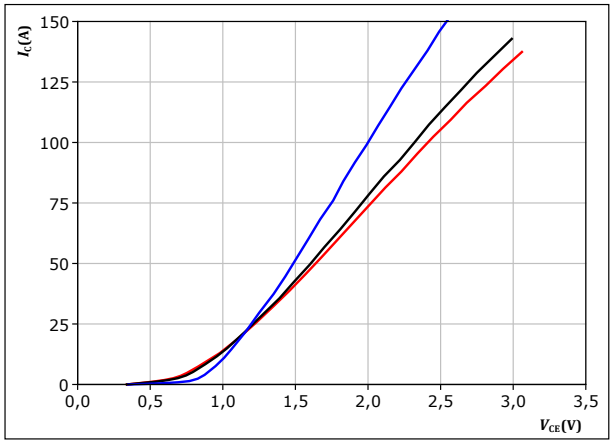
(3) Only valid with pre-applied Vincotech thermal interface material.

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

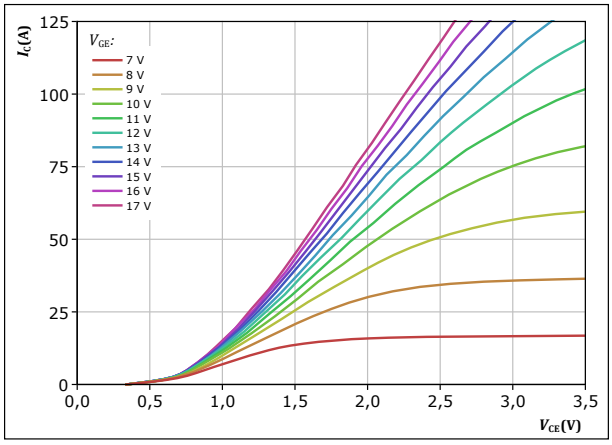


t_p =	250	µs		
V_{GE} =	15	V	T_j:	25 °C
				125 °C
				150 °C

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



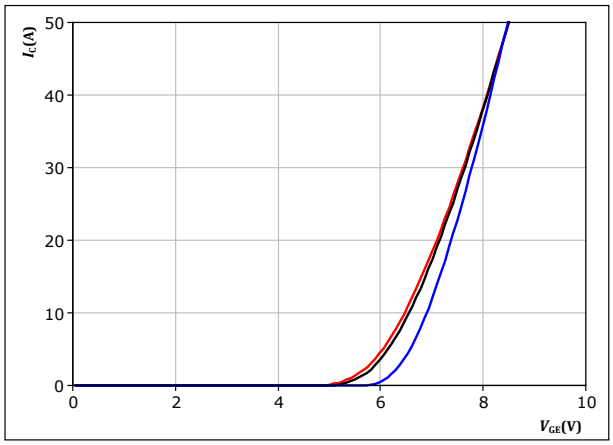
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

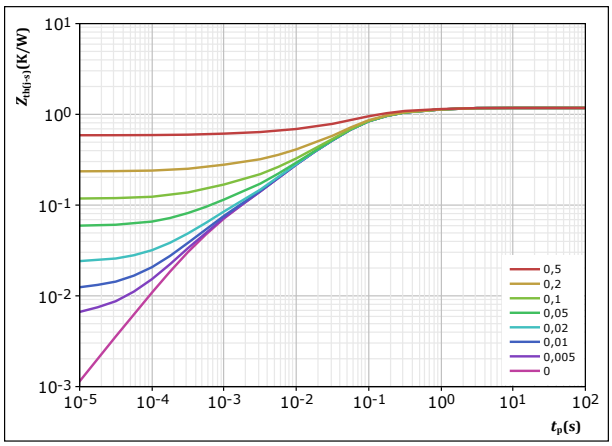


t_p =	250	µs		
V_{CE} =	10	V	T_j:	25 °C
				125 °C
				150 °C

figure 4. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,176	K/W

IGBT thermal model values

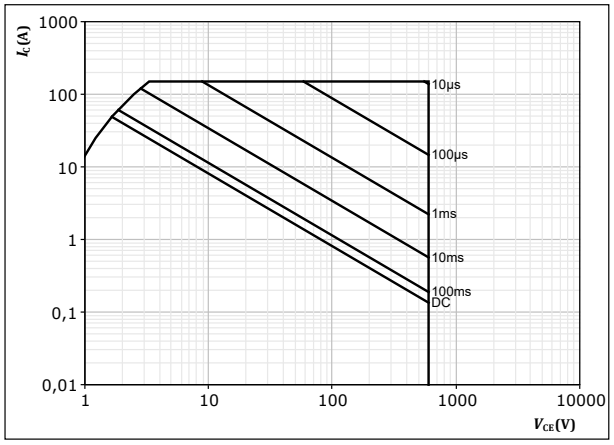
R (K/W)	τ (s)
1,28E-01	9,19E-01
3,00E-01	1,49E-01
5,67E-01	4,76E-02
1,34E-01	6,63E-03
4,70E-02	5,83E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



D = single pulse

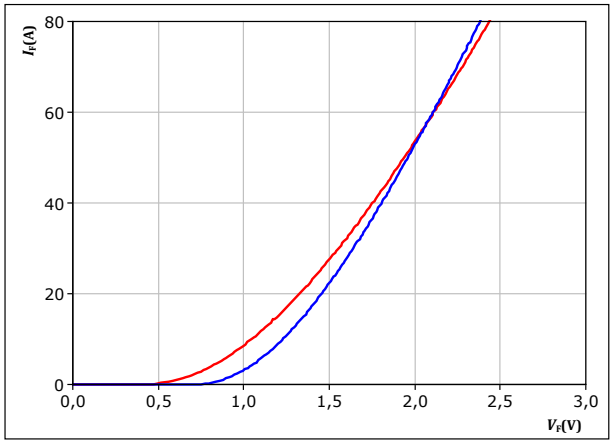
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 6. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



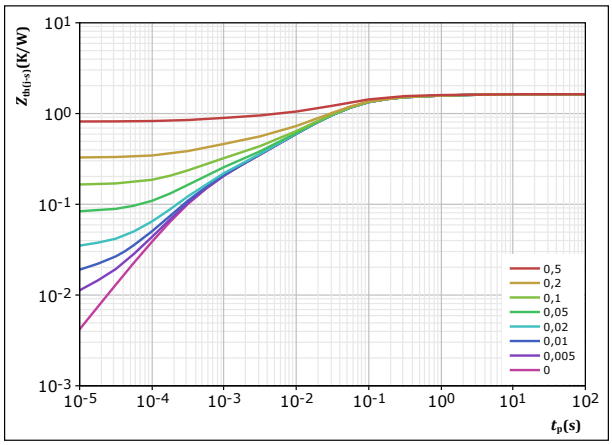
t_p = 250 µs

T_j: 25 °C, 150 °C

figure 7. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,633 K/W

FWD thermal model values

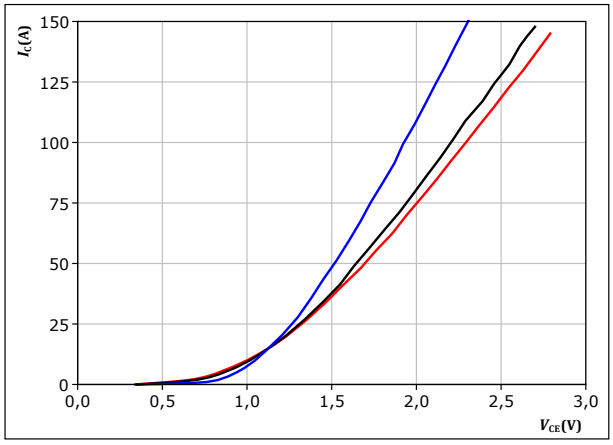
R (K/W)	τ (s)
7,13E-02	2,70E+00
1,55E-01	3,01E-01
7,25E-01	5,48E-02
3,93E-01	1,54E-02
1,57E-01	2,76E-03
1,32E-01	4,03E-04

PFC Switch Characteristics

figure 8. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

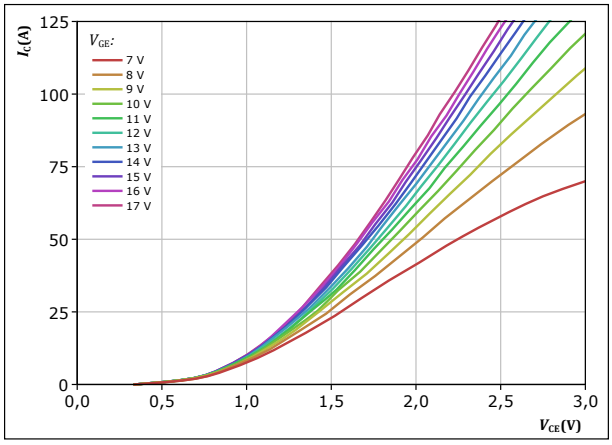


t_p =	250	µs		
V_{GE} =	15	V	T_j:	25 °C
				125 °C
				150 °C

figure 9. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



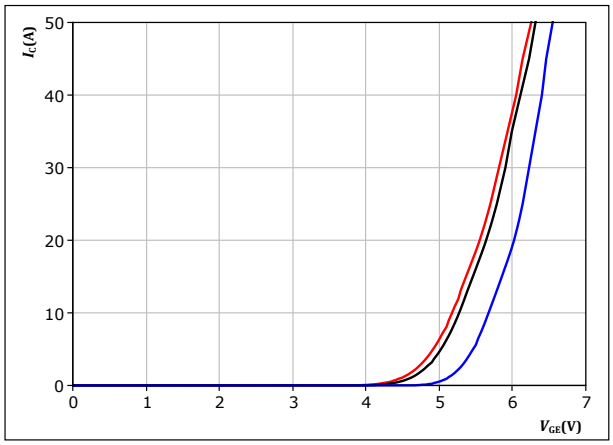
t_p =	250	µs
T_j =	150	°C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 10. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

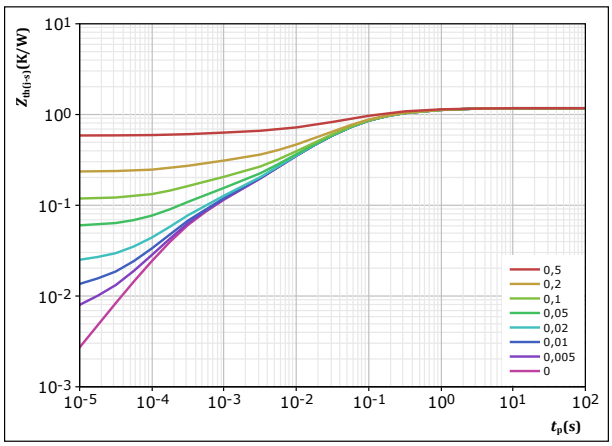


t_p =	250	µs		
V_{CE} =	10	V	T_j:	25 °C
				125 °C
				150 °C

figure 11. **IGBT**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	1,174	K/W

IGBT thermal model values

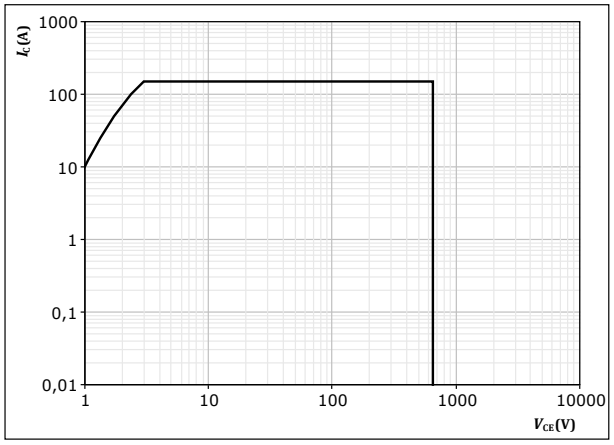
R (K/W)	τ (s)
9,21E-02	1,52E+00
2,50E-01	2,21E-01
4,87E-01	5,30E-02
2,29E-01	1,06E-02
4,67E-02	2,01E-03
6,92E-02	3,15E-04

PFC Switch Characteristics

figure 12. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



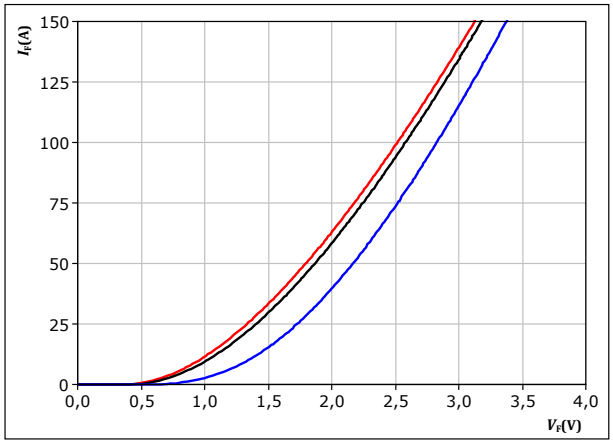
D =	single pulse	
T_s =	80	°C
V_{GE} =	15	V
T_j =	T_{jmax}	

PFC Diode Characteristics

figure 13. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



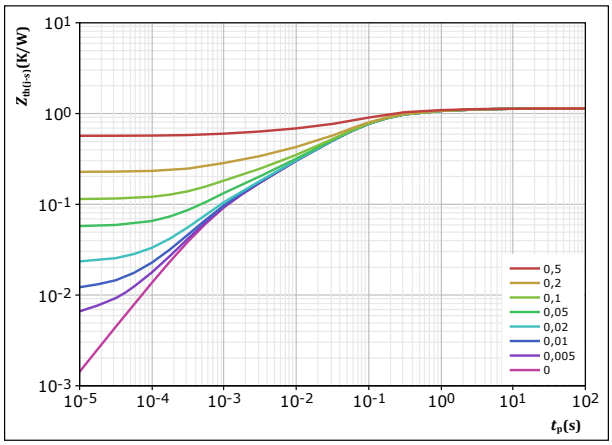
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 14. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,136 K/W

FWD thermal model values

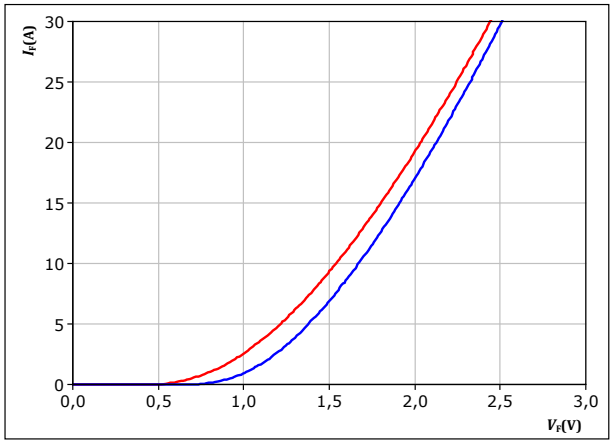
R (K/W)	τ (s)
4,89E-02	4,92E+00
1,50E-01	5,91E-01
4,68E-01	1,06E-01
2,69E-01	3,08E-02
1,24E-01	5,09E-03
7,64E-02	7,20E-04

PFC Sw. Protection Diode Characteristics

figure 15. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



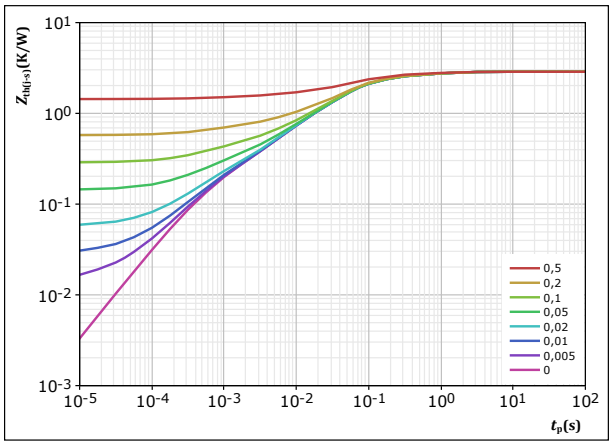
t_p = 250 µs

T_j: 25 °C, 125 °C

figure 16. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 2,874 K/W

FWD thermal model values

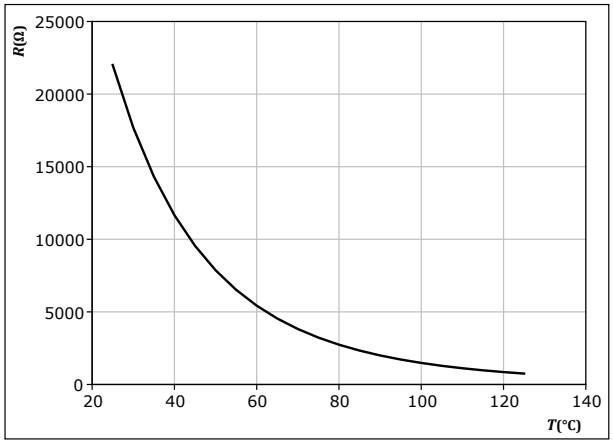
R (K/W)	τ (s)
2,86E-01	1,08E+00
5,75E-01	1,73E-01
1,57E+00	4,54E-02
3,05E-01	5,64E-03
1,34E-01	5,58E-04

Thermistor Characteristics

figure 17. **Thermistor**

Typical NTC characteristic as function of temperature

$R_T = f(T)$

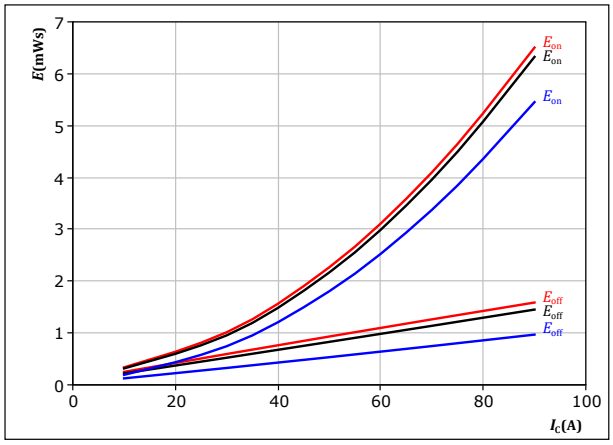


Inverter Switching Characteristics

figure 18. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



With an inductive load at

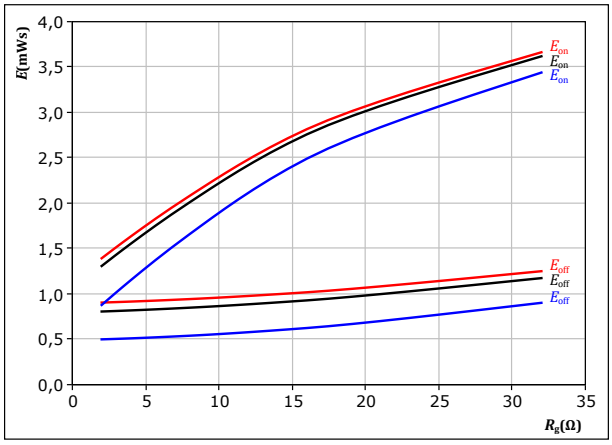
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 19. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

$E = f(R_g)$



With an inductive load at

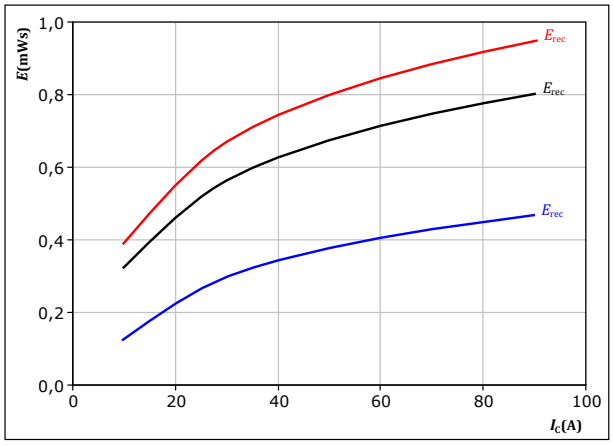
V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

T_j: 25 °C, 125 °C, 150 °C

figure 20. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



With an inductive load at

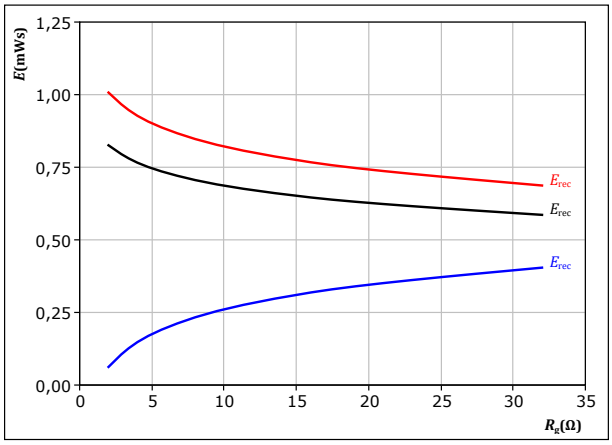
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 21. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

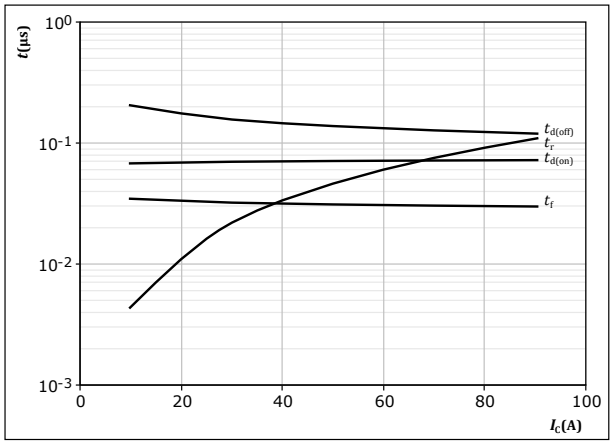
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 22. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



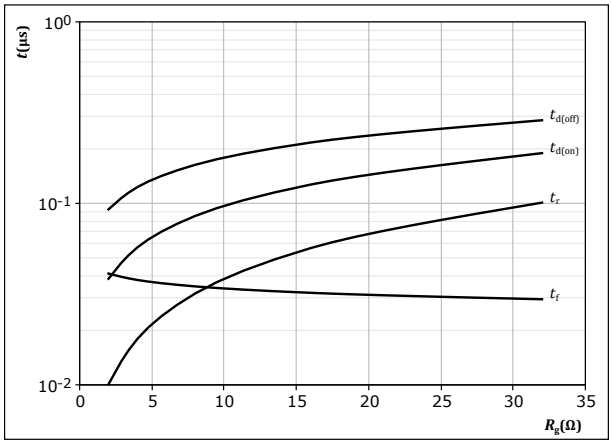
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω
R_{goff} =	8	Ω

figure 23. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

$t = f(R_g)$



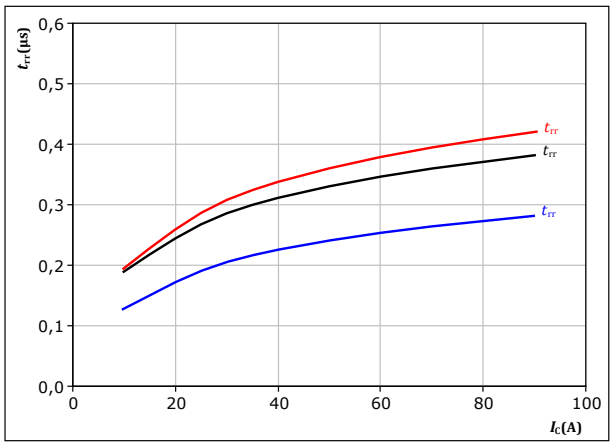
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

figure 24. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

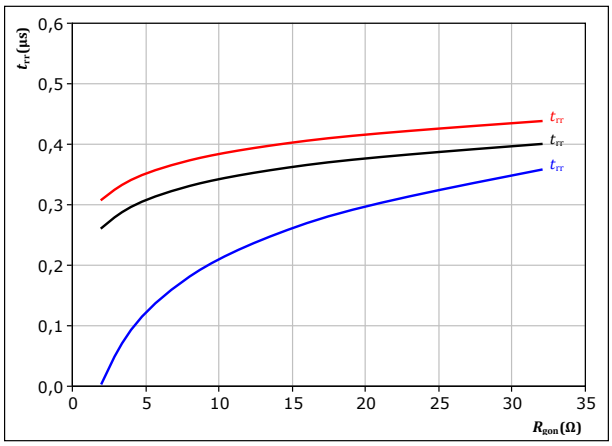
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 25. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

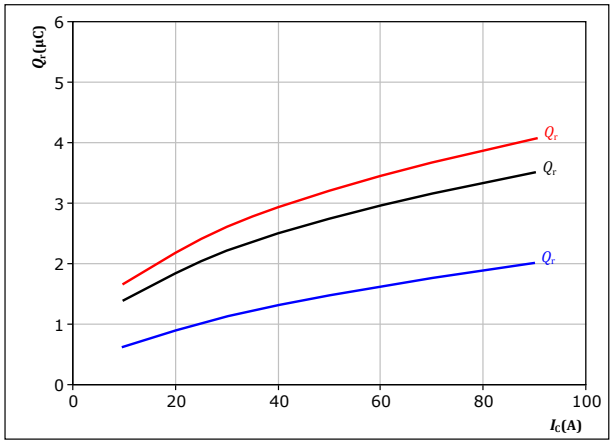
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 26. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



With an inductive load at

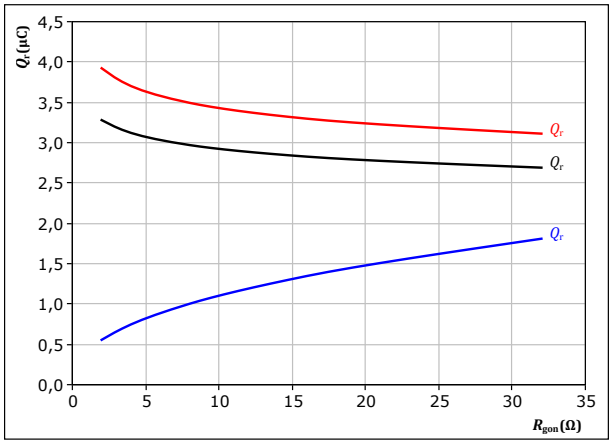
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 27. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$



With an inductive load at

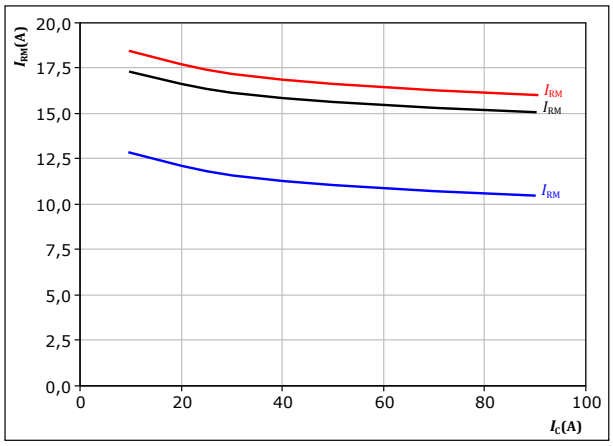
V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

T_j: 25 °C, 125 °C, 150 °C

figure 28. **FWD**

Typical peak reverse recovery current as a function of collector current

$I_{RM} = f(I_C)$



With an inductive load at

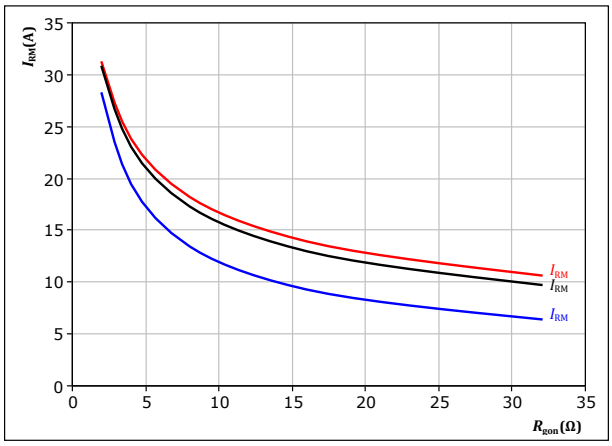
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	8	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 29. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	50	A

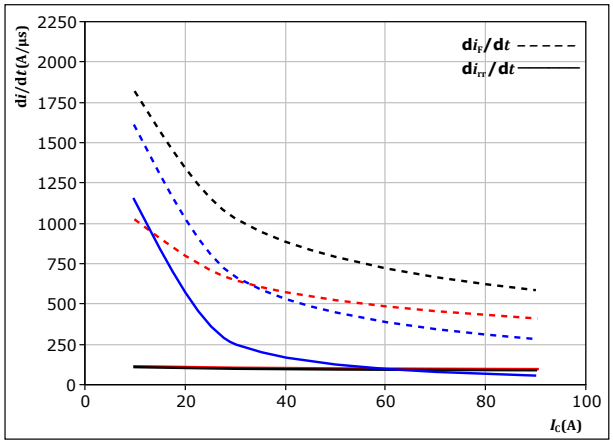
T_j: 25 °C, 125 °C, 150 °C

Inverter Switching Characteristics

figure 30. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



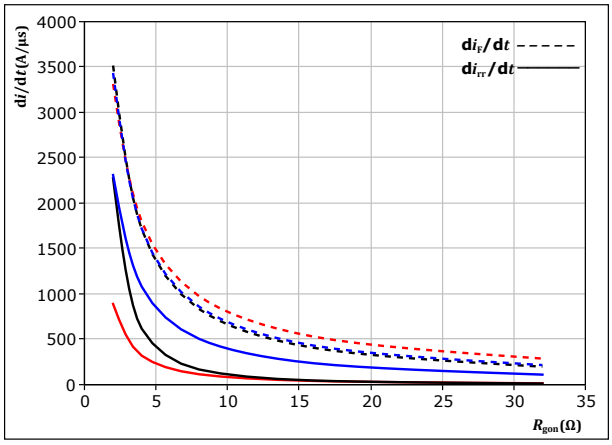
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	8	Ω		150 °C

figure 31. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



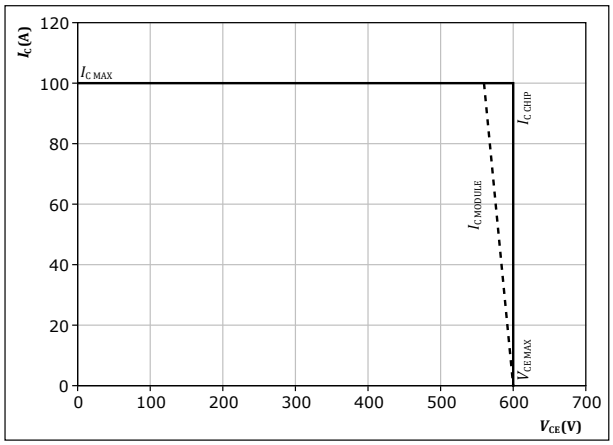
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	50	A		150 °C

figure 32. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At

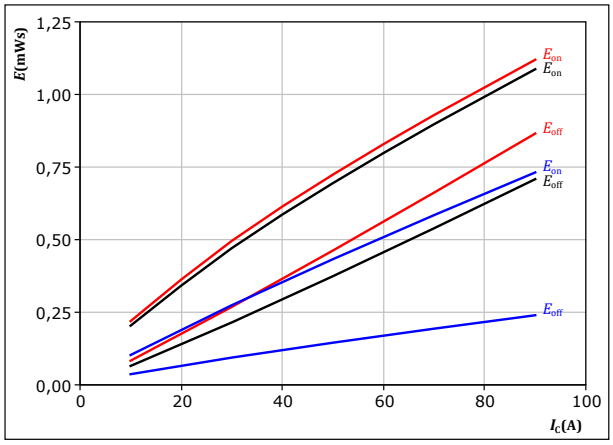
T_j =	150	°C
R_{gon} =	8	Ω
R_{goff} =	8	Ω

PFC Switching Characteristics

figure 33. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



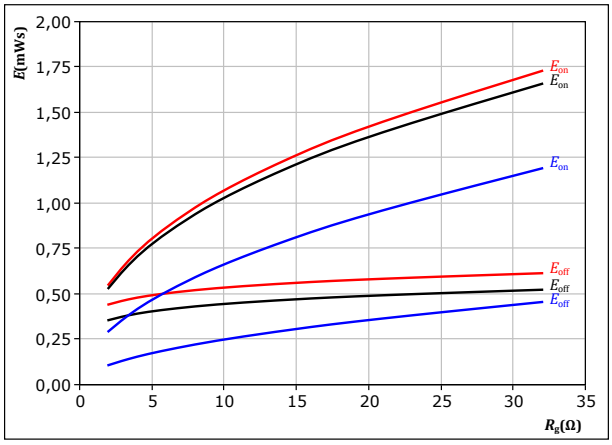
With an inductive load at

V_{CE} =	400	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
R_{gon} =	4	Ω	150 °C
R_{goff} =	4	Ω	

figure 34. **IGBT**

Typical switching energy losses as a function of IGBT turn on gate resistor

$E = f(R_g)$



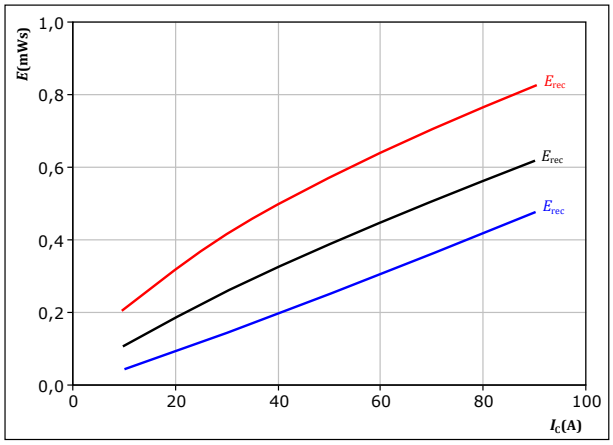
With an inductive load at

V_{CE} =	400	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
I_C =	50	A	150 °C

figure 35. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



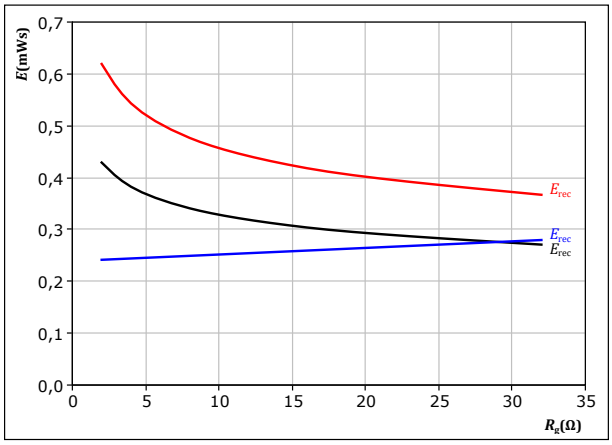
With an inductive load at

V_{CE} =	400	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
R_{gon} =	4	Ω	150 °C

figure 36. **FWD**

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

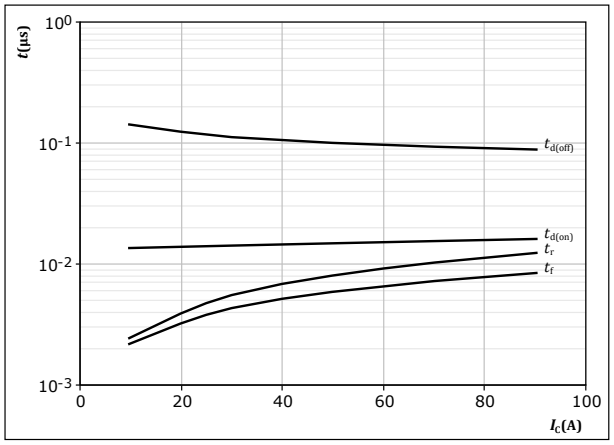
V_{CE} =	400	V	T_j: 25 °C
V_{GE} =	0/15	V	125 °C
I_C =	50	A	150 °C

PFC Switching Characteristics

figure 37. **IGBT**

Typical switching times as a function of collector current

t = f(I_C)



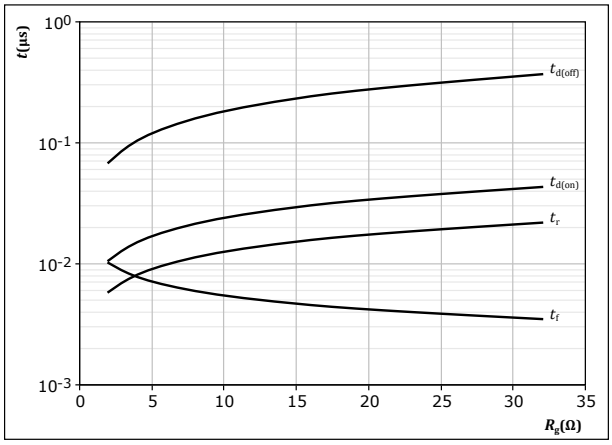
With an inductive load at

T_j =	150	°C
V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω
R_{goff} =	4	Ω

figure 38. **IGBT**

Typical switching times as a function of IGBT turn on gate resistor

t = f(R_g)



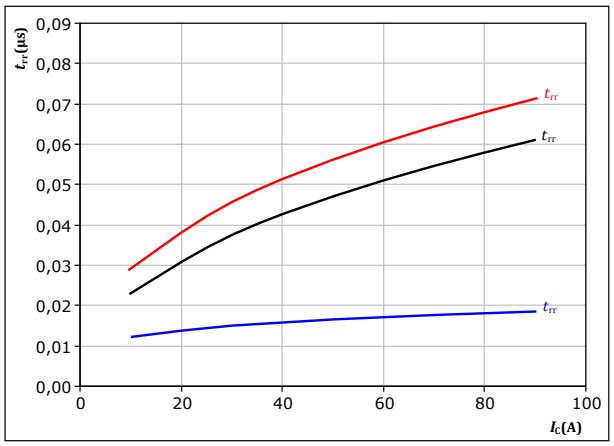
With an inductive load at

T_j =	150	°C
V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	50	A

figure 39. **FWD**

Typical reverse recovery time as a function of collector current

t_{rr} = f(I_C)



With an inductive load at

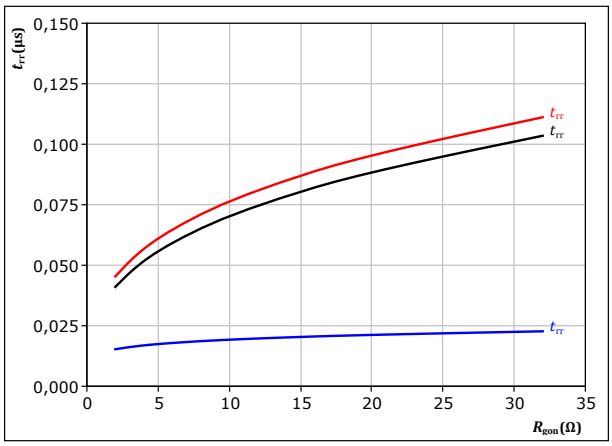
V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 40. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

t_{rr} = f(R_{gon})



With an inductive load at

V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	50	A

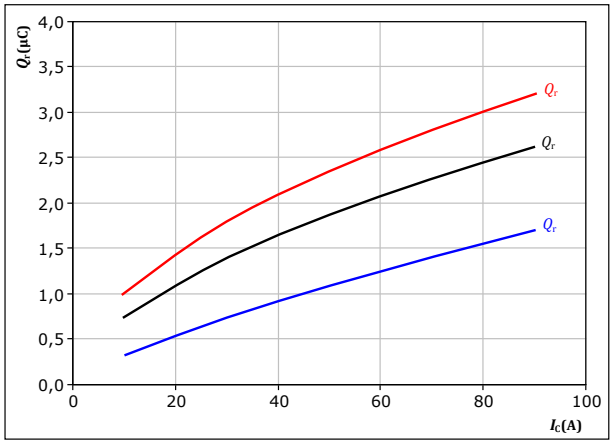
T_j: 25 °C, 125 °C, 150 °C

PFC Switching Characteristics

figure 41. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



With an inductive load at

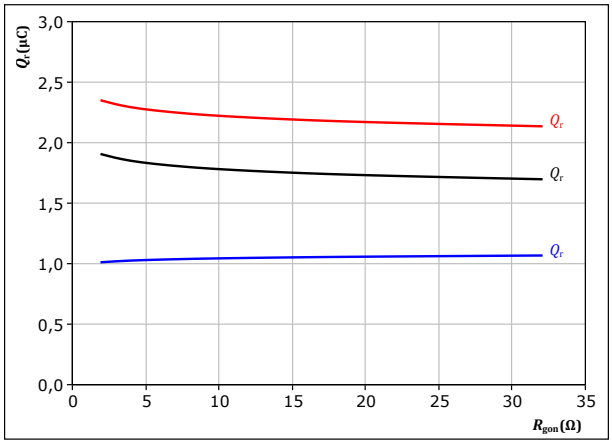
V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 42. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$



With an inductive load at

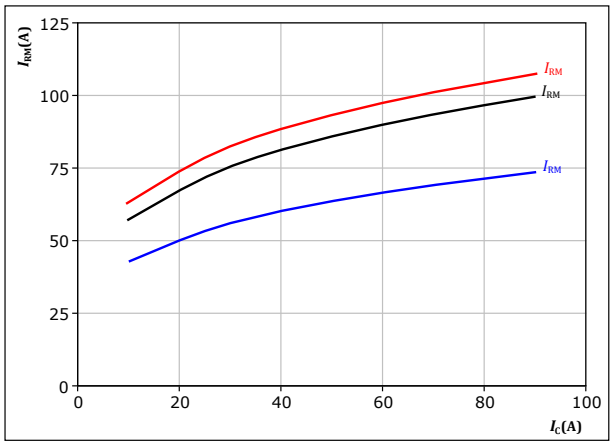
V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	50	A

T_j: 25 °C, 125 °C, 150 °C

figure 43. **FWD**

Typical peak reverse recovery current as a function of collector current

$I_{RM} = f(I_C)$



With an inductive load at

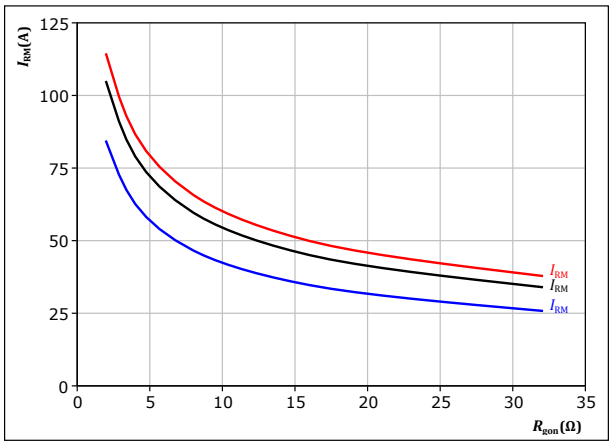
V_{CE} =	400	V
V_{GE} =	0/15	V
R_{gon} =	4	Ω

T_j: 25 °C, 125 °C, 150 °C

figure 44. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

V_{CE} =	400	V
V_{GE} =	0/15	V
I_C =	50	A

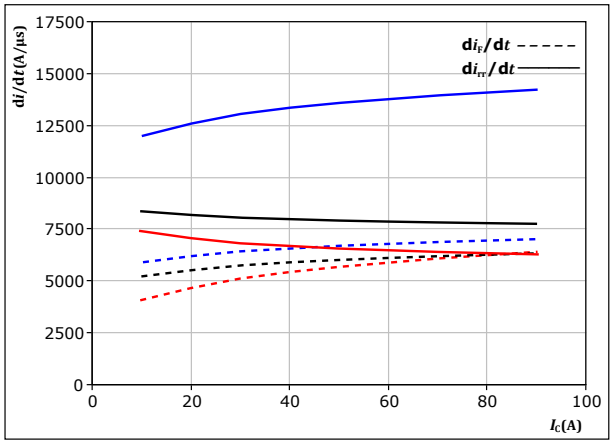
T_j: 25 °C, 125 °C, 150 °C

PFC Switching Characteristics

figure 45. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, di_{rr}/dt = f(I_C)



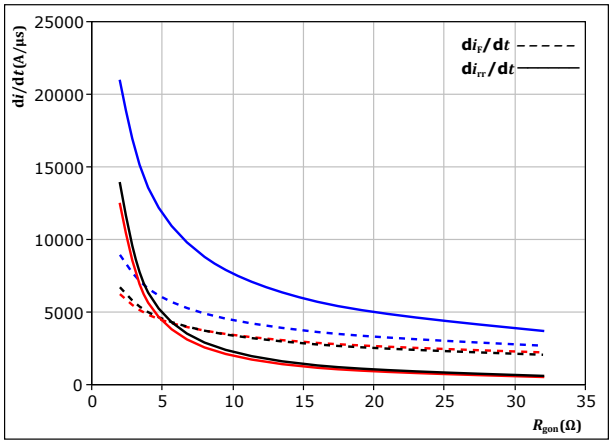
With an inductive load at

V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
R_{gon} =	4	Ω		150 °C

figure 46. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

di_F/dt, di_{rr}/dt = f(R_{gon})



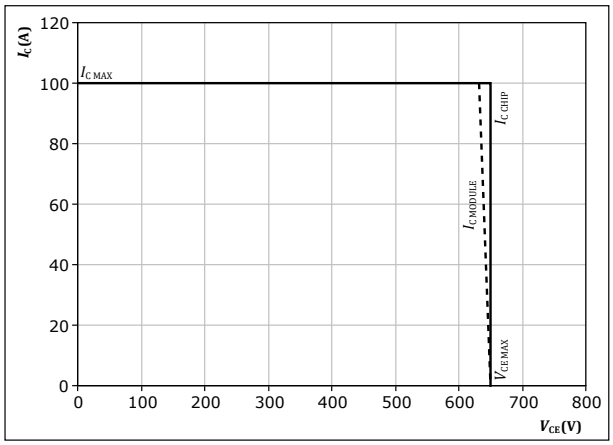
With an inductive load at

V_{CE} =	400	V	T_j:	25 °C
V_{GE} =	0/15	V		125 °C
I_C =	50	A		150 °C

figure 47. **IGBT**

Reverse bias safe operating area

I_C = f(V_{CE})



At

T_j =	150	°C	
R_{gon} =	4	Ω	
R_{goff} =	4	Ω	

Switching Definitions

figure 48. **IGBT**

Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{tEoff} = integrating time for E_{off})

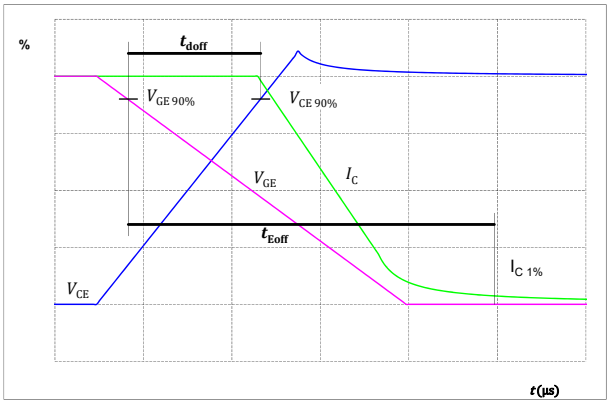


figure 49. **IGBT**

Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})

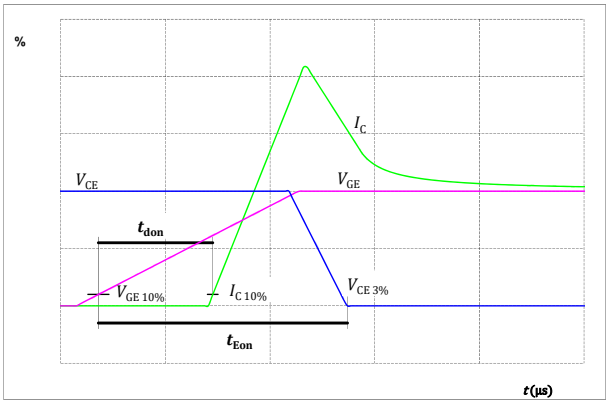


figure 50. **IGBT**

Turn-off Switching Waveforms & definition of t_f

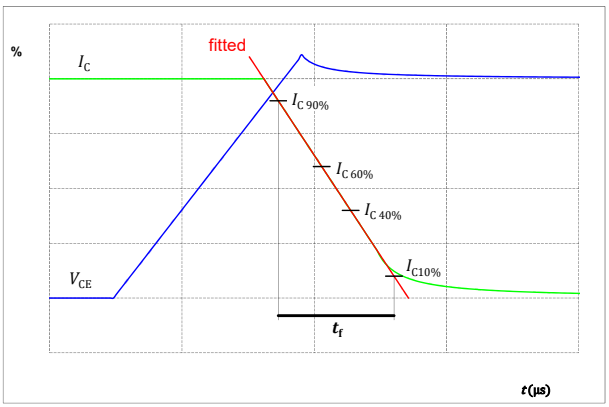
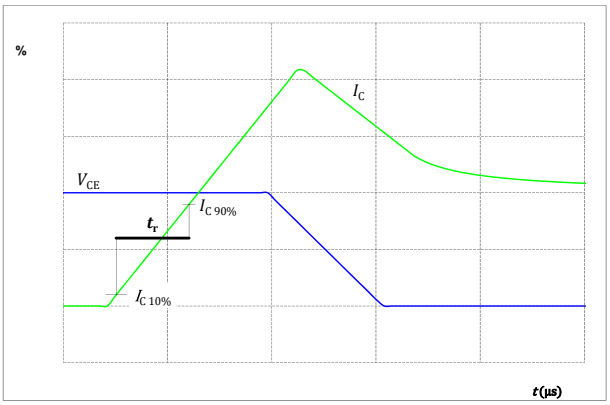


figure 51. **IGBT**

Turn-on Switching Waveforms & definition of t_r



Switching Definitions

figure 52. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

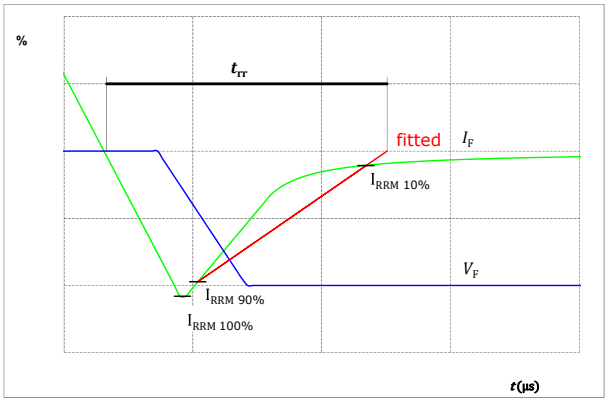
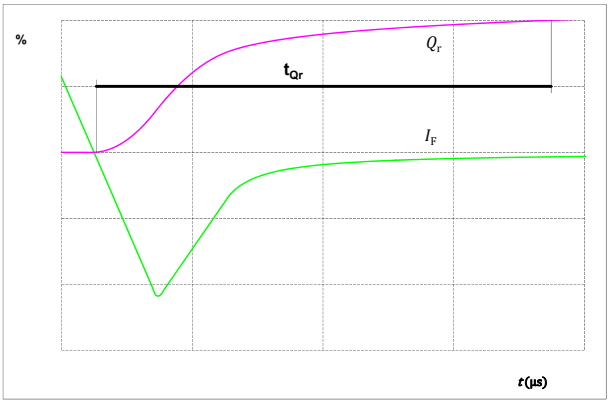


figure 53. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



Ordering Code

Version	Ordering Code
Without thermal paste	10-FE06PPA050SJ01-LH54E08Z
With thermal paste (5,2 W/mK, PTM6000HV)	10-FE06PPA050SJ01-LH54E08Z-/7/

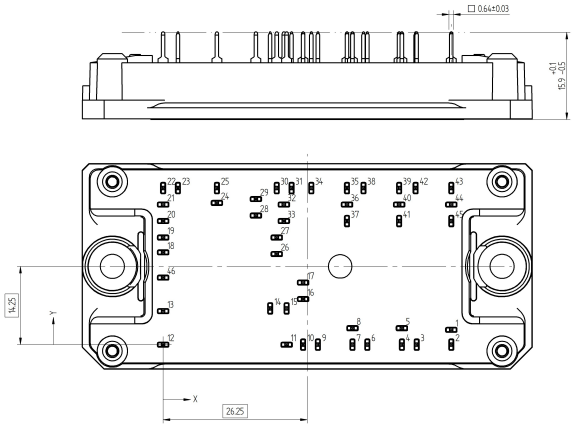
Marking

		Name		Date code	UL & VIN	Lot	Serial
Text		NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix		Type&Ver	Lot number	Serial	Date code		
		TTTTTTTVV	LLLLL	SSSS	WWYY		

Outline

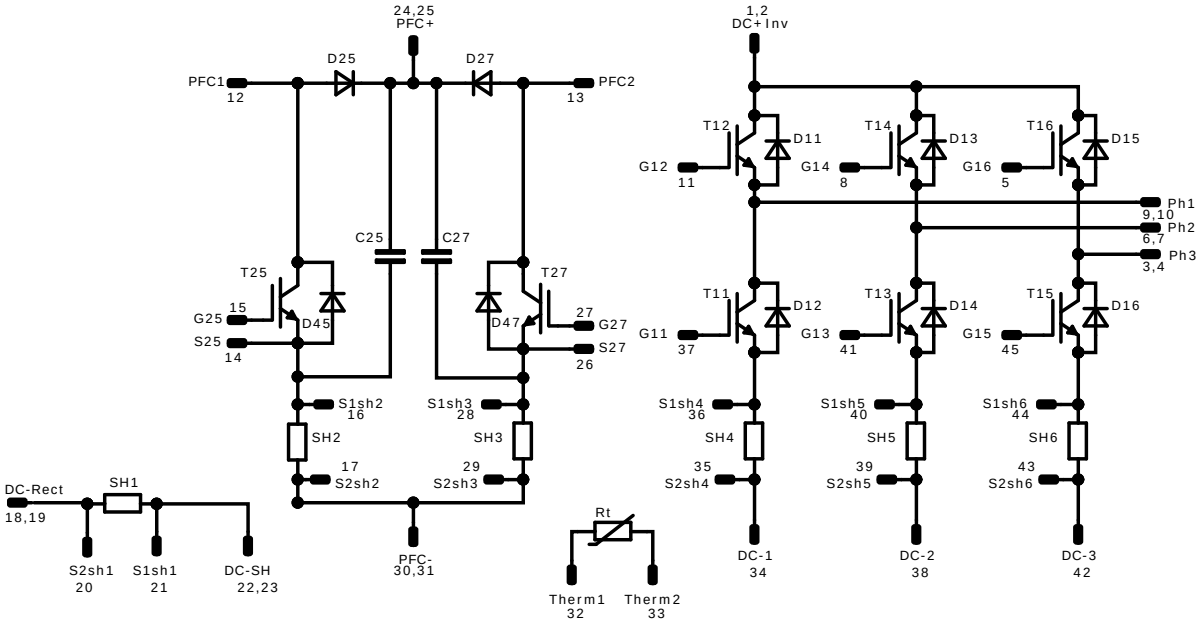
Pin table [mm]

Pin	X	Y	Function
1	52,5	2,7	DC+Inv
2	52,5	0	DC+Inv
3	46,2	0	Ph3
4	43,5	0	Ph3
5	43,5	3	G16
6	37,2	0	Ph2
7	34,5	0	Ph2
8	34,5	3	G14
9	28,2	0	Ph1
10	25,5	0	Ph1
11	22,5	0	G12
12	0	0	PFC1
13	0	6,1	PFC2
14	19,5	6,6	S25
15	22,5	6,6	G25
16	25,5	8,3	S1sh2
17	25,5	11,3	S2sh2
18	0	16,8	DC-Rect
19	0	19,5	DC-Rect
20	0	22,5	S2sh1
21	0	25,5	S1sh1
22	0	28,5	DC-SH
23	2,7	28,5	DC-SH
24	9,8	25,8	PFC+
25	9,8	28,5	PFC+
26	20,7	16,5	S27
27	20,7	19,5	G27
28	16,9	23,5	S1sh3
29	16,9	26,5	S2sh3
30	20,7	28,5	PFC-
31	23,4	28,5	PFC-
32	22	25,5	Therm1
33	22	22,5	Therm2
34	27	28,5	DC-1
35	33,5	28,5	S2sh4
36	33,5	25,5	S1sh4
37	33,5	22,5	G11
38	36,5	28,5	DC-2
39	43	28,5	S2sh5
40	43	25,5	S1sh5
41	43	22,5	G13
42	46	28,5	DC-3
43	52,5	28,5	S2sh6
44	52,5	25,5	S1sh6
45	52,5	22,5	G15
46	not assembled		



Tolerance of pinpositions ±0.4mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification					
ID	**Component**	**Voltage**	**Current**	**Function**	**Comment**
T11, T12, T13, T14, T15, T16	IGBT	600 V	50 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	600 V	30 A	Inverter Diode	
T25, T27	IGBT	650 V	50 A	PFC Switch	
D25, D27	FWD	650 V	50 A	PFC Diode	
D45, D47	FWD	650 V	10 A	PFC Sw. Protection Diode	
SH4, SH5, SH6	Shunt			Inverter Shunt	
SH2, SH3	Shunt			PFC Shunt	
SH1	Shunt			Shunt	
C25, C27	Capacitor	630 V		Capacitor (PFC)	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 1 packages see vincotech.com website.

Package data
Package data for *flow* 1 packages see vincotech.com website.

Vincotech thermistor reference
See Vincotech thermistor reference table at vincotech.com website.

UL recognition and file number
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}$=175°C and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-FE06PPA050SJ01-LH54E08Z-D1-14	10 Mar. 2025	Initial Release	